



QPD3640 150 W / 300 W, 48 V, 3.4 – 3.8 GHz, Asymmetric Doherty

Product Overview

The QPD3640 is a dual-path discrete GaN on SiC HEMT which operates on LTE downlink Band 42 (3.4-3.6 GHz) and Band 43 (3.6-3.8 GHz). The device is a single-stage, matched, power Doherty amplifier transistor.

QPD3640 can deliver P4dB of 389 W at +50 V operation.

Lead free and RoHS compliant.



4-Lead NI780 Package

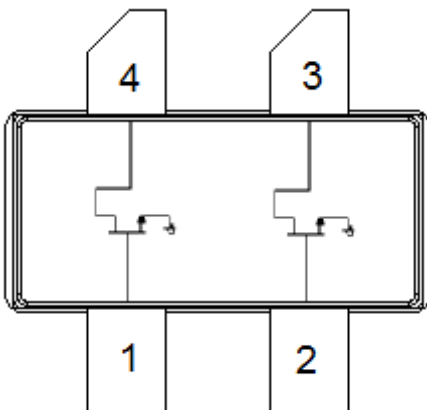
Key Features

- Operating Frequency Range: 3.4 – 3.8 GHz
- Operating Drain Voltage: +48 V
- Doherty Output Power at P4dB: 389 W ⁽¹⁾
- Doherty Drain Efficiency P4dB: 57.4% ⁽¹⁾
- Doherty Linear Gain: 15.6 dB ⁽¹⁾
- 4-Lead, Earless, Ceramic NI780 Package

Note:

1. Based on pulsed P4dB performance at 3.75 GHz.

Functional Block Diagram



Applications

- WCDMA / LTE
- Macrocell Base Station
- Asymmetric Doherty Applications

Ordering Information

Part Number	Description
QPD3640SR	Short Reel – 100 Pieces
QPD3640TR13	13" Reel – 2500 Pieces
QPD3640EVB02	3.5 – 3.7 GHz Doherty Eval. Board
QPD3640EVB03	3.4 – 3.6 GHz Doherty Eval. Board
QPD3640EVB04	3.6 – 3.8 GHz Doherty Eval. Board

Absolute Maximum Ratings

Parameter	Rating
Breakdown Voltage (V_{DG})	+165 V
Gate Voltage Range ($V_{G1,2}$)	-7 to +2 V
Drain Voltage ($V_{D1,2}$)	+55 V
Peak RF Input Power	+42 dBm
VSWR Mismatch, P1dB Pulse (10% Duty Cycle, 100 μ s Width), T = +25°C	10:1
Storage Temperature	-65 to +150°C

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to device may reduce device reliability.

Recommended Operating Conditions

Parameter	Min	Typ	Max	Unit
Carrier Gate Voltage (V_{G1})		-2.8		V
Peaking Gate Voltage (V_{G2})		-5.5		V
Drain Voltage ($V_{D1,2}$)		+48		V
Carrier Quiescent Current (I_{BQ1})		342		mA

Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.

Electrical Specifications

Parameter	Conditions	Min	Typ	Max	Units
Operational Frequency Range		3600		3800	MHz
Carrier Quiescent Drain Current			342		mA
Linear Doherty Gain	P4dB		15.6		dB
Doherty Output Power	P4dB		55.9		dBm
Doherty Drain Efficiency	P4dB		57.4		%
Carrier Amplifier Gate Leakage			27.5		mA
Peaking Amplifier Gate Leakage			48.0		mA

Test conditions unless otherwise noted: $V_{D1,2} = +50$ V, $I_{BQ1} = 342$ mA, $V_{G2} = -5.5$ V, T = +25°C, Pulsed (10% Duty Cycle, 100 μ s Width) at 3750 MHz on a reference design fixture.

Thermal Information

Parameter	Conditions	Values	Units
Thermal Resistance, Peak IR Surface Temperature at Average Power (θ_{JC})	T _{CASE} = +105°C, T _{CH} = 144°C CW: P _{DISS} = 36.9 W, P _{OUT} = 42.2 W	1.1	°C/W

Notes:

1. Based on expected carrier amplifier efficiency of Doherty.
2. P_{OUT} assumes 25% peaking amplifier contribution of total average Doherty rated power.
3. Thermal resistance is measured to package backside.
4. Refer to the following document: [GaN Device Channel Temperature, Thermal Resistance, and Reliability Estimates](#)

Carrier Amplifier Power-Matched Load Pull Performance

Frequency (MHz)	Source Impedance (Ω)	Load Impedance (Ω)	P3dB (dBm)	Drain Efficiency (%)	G3dB (dB)
3400	5.42 – j18.78	5.79 – j1.66	53.5	60.8	16.2
3600	8.92 – j22.51	3.84 – j2.29	53.5	59.7	16.9
3800	13.12 – j9.38	3.06 – j4.53	53.2	57.1	15.7

Test conditions unless otherwise noted: $V_{D1} = +50\text{ V}$, $I_{DQ1} = 342\text{ mA}$, $T = +25^\circ\text{C}$, Pulsed (10% Duty Cycle, 100 μs Width), P3dB.

Carrier Amplifier Efficiency-Matched Load Pull Performance

Frequency (MHz)	Source Impedance (Ω)	Load Impedance (Ω)	P3dB (dBm)	Drain Efficiency (%)	G3dB (dB)
3400	5.42 – j18.78	10.84 – j7.86	51.6	73.1	18.6
3600	8.92 – j22.51	11.09 – j1.54	51.4	72.7	20.1
3800	13.12 – j9.38	5.40 – j2.12	52.1	68.1	18.2

Test conditions unless otherwise noted: $V_{D1} = +50\text{ V}$, $I_{DQ1} = 342\text{ mA}$, $T = +25^\circ\text{C}$, Pulsed (10% Duty Cycle, 100 μs Width), P3dB.

Peaking Amplifier Power-Matched Load Pull Performance

Frequency (MHz)	Source Impedance (Ω)	Load Impedance (Ω)	P1dB (dBm)	Drain Efficiency (%)	G1dB (dB)
3400	3.81 – j15.15	11.42 – j7.78	55.2	62.2	15.0
3600	10.48 – j14.41	9.16 – j4.02	55.1	59.9	14.8
3800	5.02 – j4.01	7.68 – j2.60	55.2	58.1	13.9

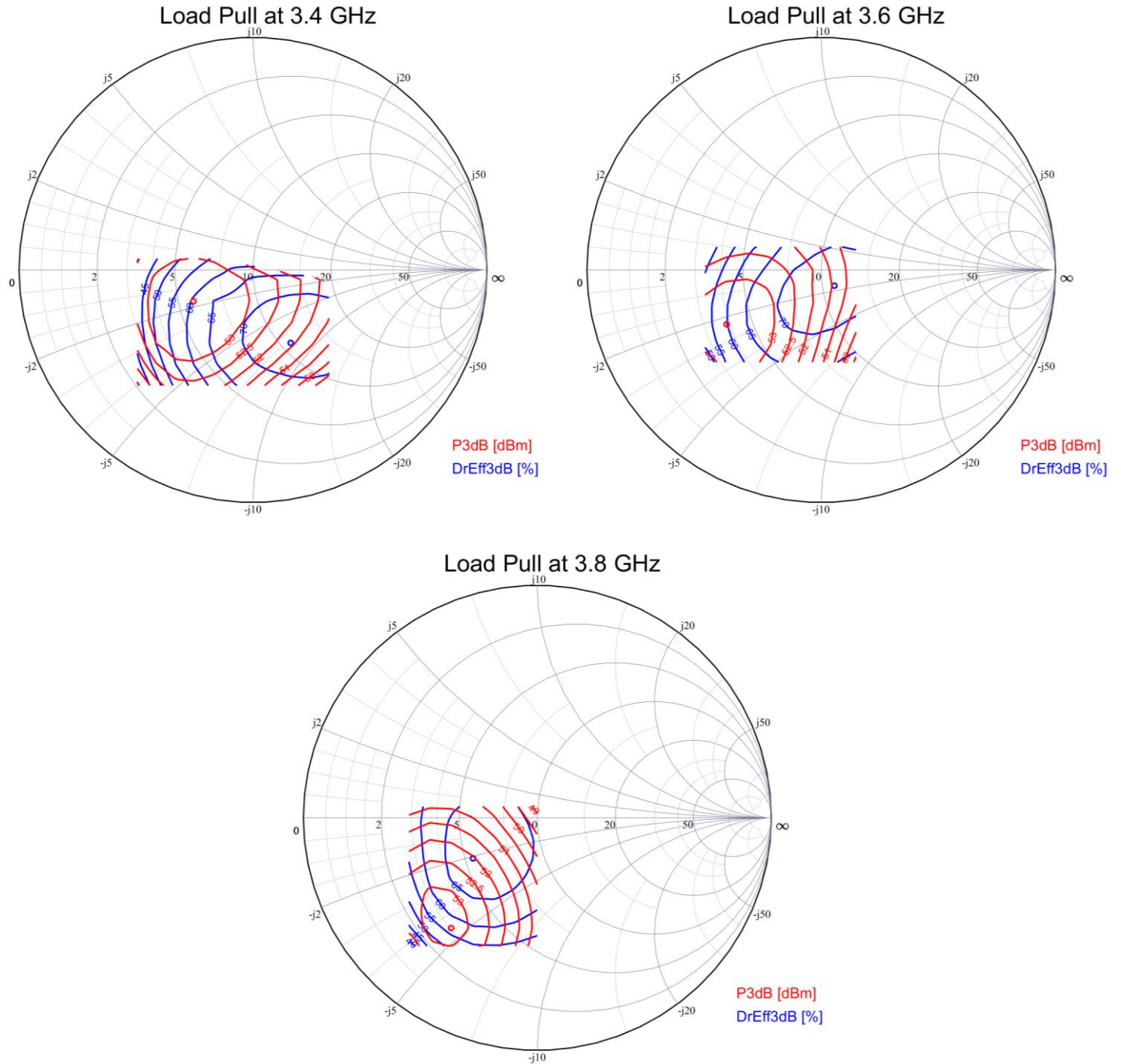
Test conditions unless otherwise noted: $V_{D2} = +50\text{ V}$, $V_{G2} = -4.5\text{ V}$, $T = +25^\circ\text{C}$, Pulsed (10% Duty Cycle, 100 μs Width), P1dB.

Peaking Amplifier Efficiency-Matched Load Pull Performance

Frequency (MHz)	Source Impedance (Ω)	Load Impedance (Ω)	P1dB (dBm)	Drain Efficiency (%)	G1dB (dB)
3400	3.81 – j15.15	6.34 – j13.35	53.7	73.9	16.0
3600	10.48 – j14.41	9.15 – j11.99	53.5	71.7	15.6
3800	5.02 – j4.01	13.28 – j9.19	53.7	68.2	14.4

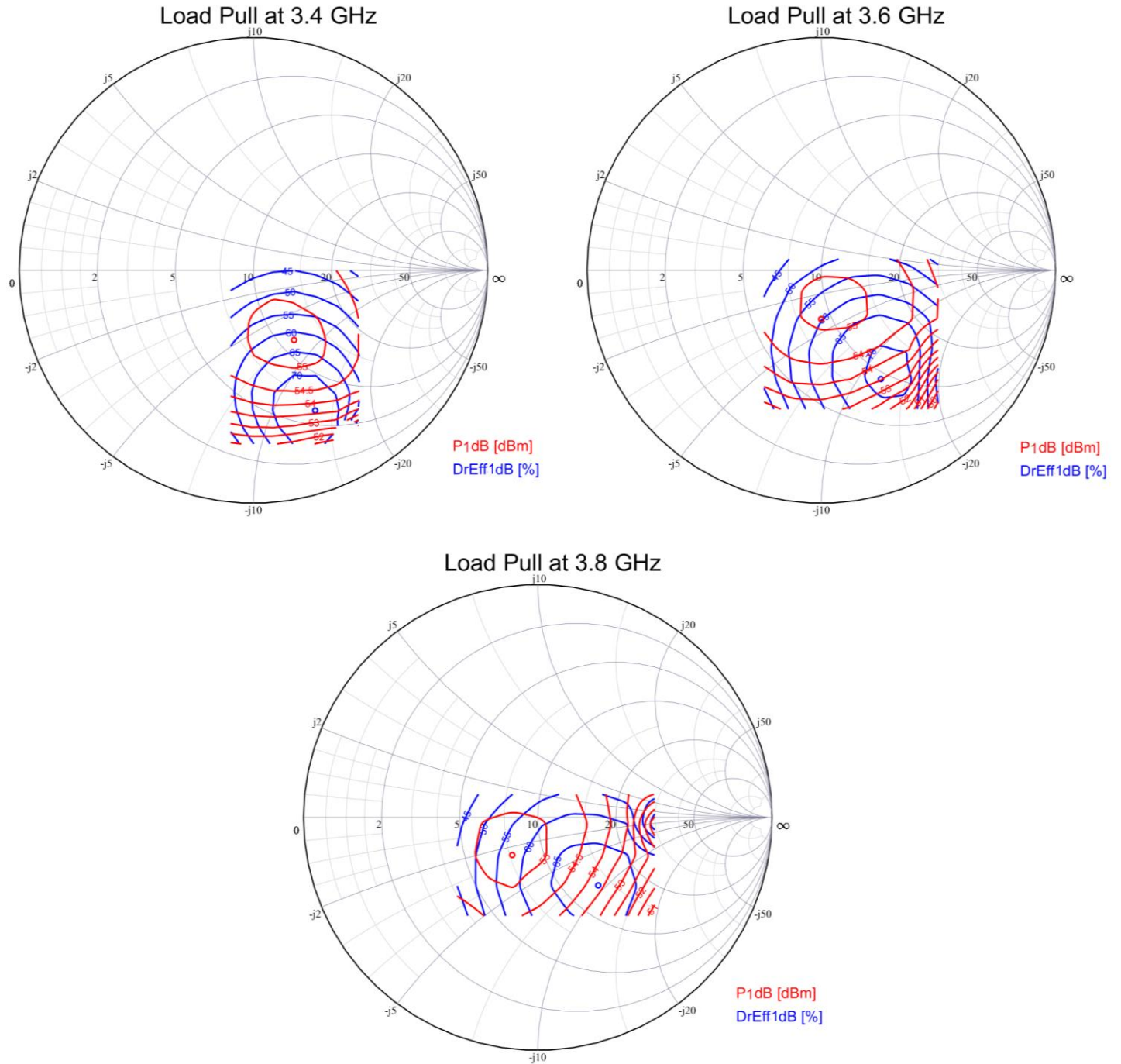
Test conditions unless otherwise noted: $V_{D2} = +50\text{ V}$, $V_{G2} = -4.5\text{ V}$, $T = +25^\circ\text{C}$, Pulsed (10% Duty Cycle, 100 μs Width), P1dB.

Carrier Amplifier Load Pull Plots



Test conditions unless otherwise noted: $V_{D1} = +50$ V, $I_{DQ1} = 342$ mA, $T = +25^{\circ}\text{C}$, Pulsed (10% Duty Cycle, 100 μs Width), P3dB.

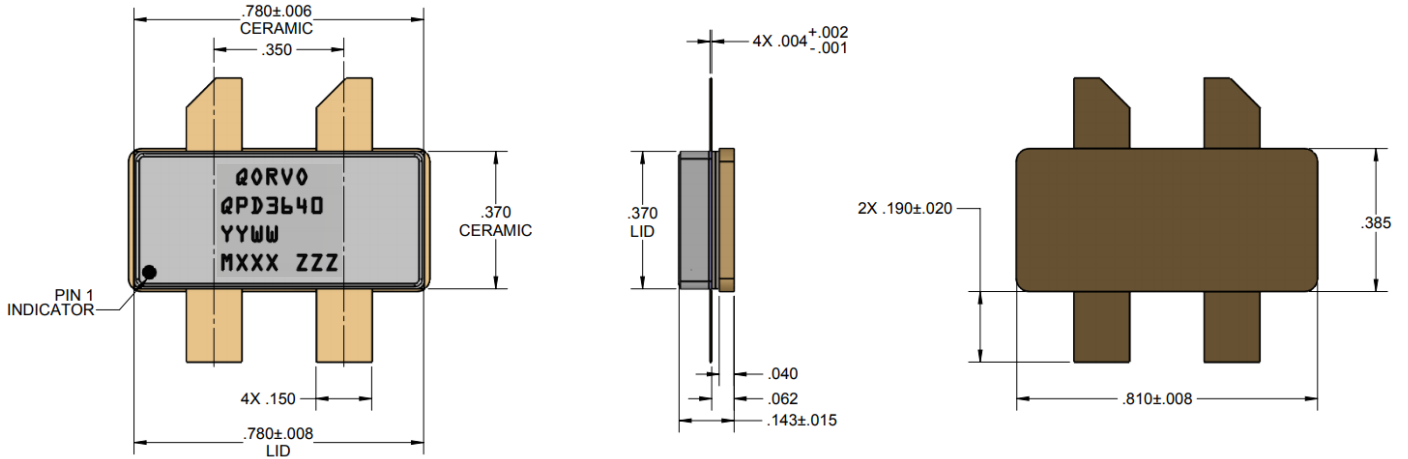
Peaking Amplifier Load Pull Plots



Test conditions unless otherwise noted: $V_{D2} = +50\text{ V}$, $V_{G2} = -4.5\text{ V}$, $T = +25^\circ\text{C}$, Pulsed (10% Duty Cycle, 100 μs Width), P1dB.

Package Marking and Dimensions

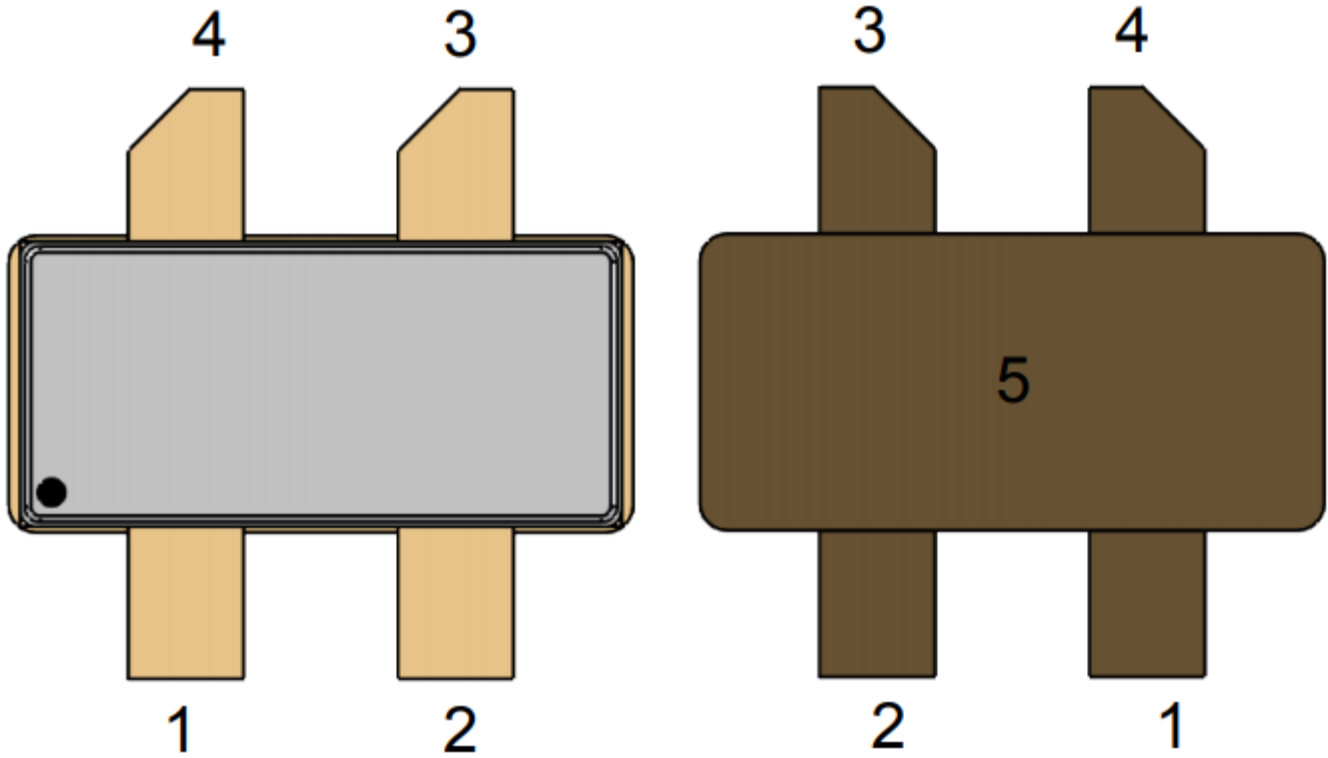
Marking: Qorvo Logo
 Part Number – QPD3640
 Date Code – YYWW
 Lot Code – MXXX
 Serial Number – ZZZ



Notes: Unless Otherwise Specified;

1. Material:
 - Package Base: Ceramic/Metal
 - Package Lid: Ceramic
2. Package exposed metal base and leads are NiAu plated. Au thickness is minimum 60 μm .
3. Part is epoxy sealed.
4. Part meets industry standard NI780 footprint.
5. Body dimensions do not include lid shift or epoxy run out, which can be up to 0.020 inches per side.
6. All dimensions are in inches. Angles are in degrees.
7. General tolerance is ± 0.005 unless otherwise shown.

Pin Configuration and Description



Top View

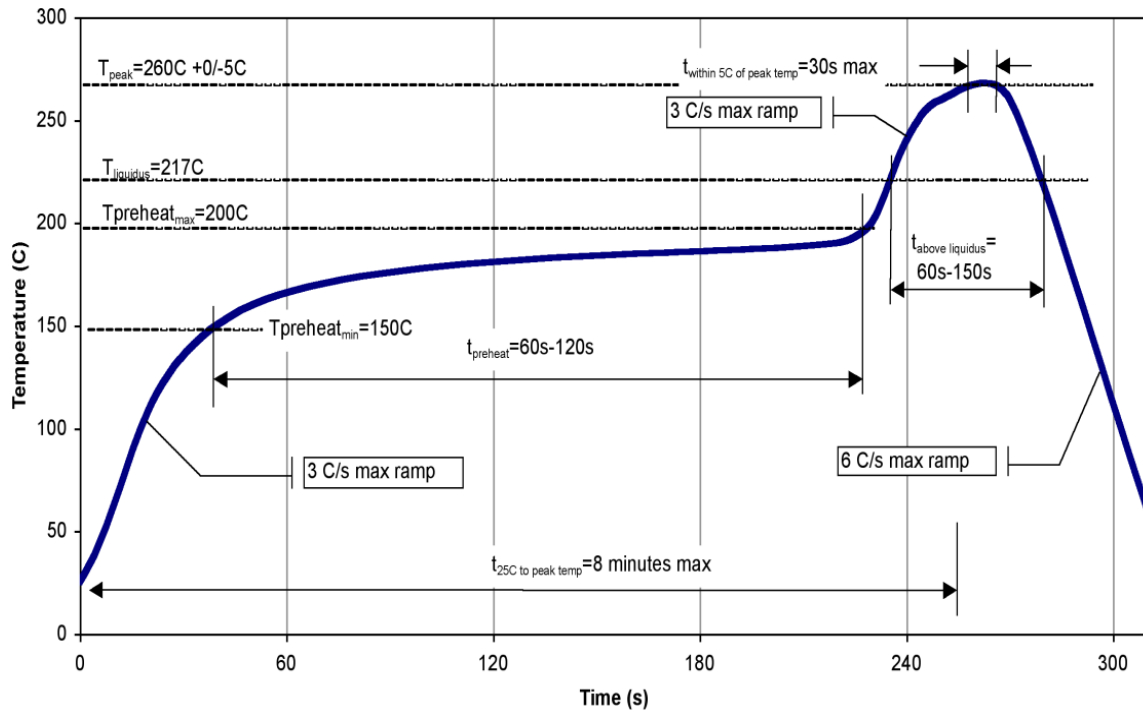
Bottom View

Pin Number	Label	Description
1	RF IN 1, VG1	Carrier Amplifier RF Input, Gate Bias
2	RF IN 2, VG2	Peaking Amplifier RF Input, Gate Bias
3	RF OUT 2, VD2	Peaking Amplifier RF Output, Drain Bias
4	RF OUT 1, VD1	Carrier Amplifier RF Output, Drain Bias
5 (Backside Paddle)	RF/DC GND	RF/DC Ground

Doherty Biasing Procedure

Bias On	Bias Off
<ol style="list-style-type: none"> 1. Turn ON V_{G1} and V_{G2} to -4 V. 2. Turn ON V_{D1} and V_{D2} to $+50$ V. 3. Adjust V_{G2} until $I_{D2} = 600$ mA (V_{G2_SET}). 4. Subtract 2.5 V from V_{G2_SET} ($V_{G2} = V_{G2_SET} - 2.5$ V). (Typically, $V_{G2} = -5.5$ V.) 5. Adjust V_{G1} until $I_{D1} = 342$ mA. (Typically, $V_{G1} = -2.8$ V.) 6. Turn ON RF. 	<ol style="list-style-type: none"> 1. Turn OFF RF. 2. Adjust V_{G1} and V_{G2} to -5 V. 3. Turn OFF V_{D1} and V_{D2}. 4. Wait two (2) seconds to allow drain capacitor charge to dissipate. 5. Turn OFF V_{G1} and V_{G2}.

Recommended Solder Temperature Profile



Handling Precautions

Parameter	Rating	Standard
ESD – Human Body Model (HBM)	Class 1B (500 V)	ANSI/ESDA/JEDEC Standard JS-001
ESD – Charged Device Model (CDM)	Class C3 (1000 V)	ANSI/ESDA/JEDEC Standard JS-002
MSL – Moisture Sensitivity Level	Level 3	IPC/JEDEC Standard J-STD-020



Solderability

Compatible with lead-free (260°C maximum reflow temperature) soldering processes.
 The use of no-clean solder to avoid washing after soldering is recommended.
 Package lead plating is NiAu. Au thickness is minimum 60 µin.

RoHS Compliance

This part is compliant with 2011/65/EU RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment) as amended by Directive 2015/863/EU.

This product also has the following attributes:

- Lead Free
- Antimony Free
- TBBP-A (C₁₅H₁₂Br₄O₂) Free
- PFOS Free
- SVHC Free



Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations:

Web: www.qorvo.com

Tel: 1-844-890-8163

Email: customer.support@qorvo.com

Important Notice

The information contained herein is believed to be reliable; however, Qorvo makes no warranties regarding the information contained herein and assumes no responsibility or liability whatsoever for the use of the information contained herein. All information contained herein is subject to change without notice. Customers should obtain and verify the latest relevant information before placing orders for Qorvo products. The information contained herein or any use of such information does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other intellectual property rights, whether with regard to such information itself or anything described by such information. **THIS INFORMATION DOES NOT CONSTITUTE A WARRANTY WITH RESPECT TO THE PRODUCTS DESCRIBED HEREIN, AND QORVO HEREBY DISCLAIMS ANY AND ALL WARRANTIES WITH RESPECT TO SUCH PRODUCTS WHETHER EXPRESS OR IMPLIED BY LAW, COURSE OF DEALING, COURSE OF PERFORMANCE, USAGE OF TRADE OR OTHERWISE, INCLUDING THE IMPLIED WARRANTIES OF MERCHANTABILITY AND FITNESS FOR A PARTICULAR PURPOSE.**

Without limiting the generality of the foregoing, Qorvo products are not warranted or authorized for use as critical components in medical, life-saving, or life-sustaining applications, or other applications where a failure would reasonably be expected to cause severe personal injury or death.

Copyright 2019 © Qorvo, Inc. | Qorvo is a registered trademark of Qorvo, Inc.